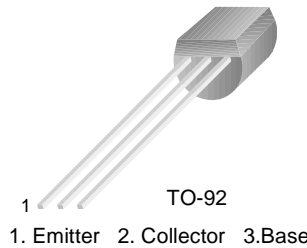


FJN3303

NPN Silicon Transistor Planar Silicon Transistor

High Voltage Switch Mode Application

- High Speed Switching
- Suitable for Electronic Ballast and Charger



Absolute Maximum Ratings $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	700	V
V_{CEO}	Collector-Emitter Voltage	400	V
V_{EBO}	Emitter-Base Voltage	9	V
I_C	Collector Current (DC)	1.5	A
I_{CP}	Collector Current (Pulse) *	3	A
I_B	Base Current (DC)	0.75	A
I_{BP}	Base Current (Pulse) *	1.5	A
P_C	Collector Power Dissipation ($T_C = 25^\circ\text{C}$)	1.1	W
T_J	Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-65 ~ 150	$^\circ\text{C}$

* Pulse Test: Pulse Width = 5ms, Duty Cycle \leq 10%

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
BV_{CBO}	Collector-Base Breakdown Voltage	$I_C = 500\mu\text{A}, I_E = 0$	700			V
BV_{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 5\text{mA}, I_B = 0$	400			V
BV_{EBO}	Emitter-Base Breakdown Voltage	$I_E = 500\mu\text{A}, I_C = 0$	9			V
I_{CBO}	Collector Cut-off Current	$V_{CB} = 700\text{V}, I_E = 0$			10	μA
I_{EBO}	Emitter Cut-off Current	$V_{EB} = 9\text{V}, I_C = 0$			10	μA
h_{FE1} h_{FE2}	DC Current Gain	$V_{CE} = 2\text{V}, I_C = 0.5\text{A}$ $V_{CE} = 2\text{V}, I_C = 1.0\text{A}$	14 5		23	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 0.5\text{A}, I_B = 0.1\text{A}$ $I_C = 1.0\text{A}, I_B = 0.25\text{A}$ $I_C = 1.5\text{A}, I_B = 0.5\text{A}$			0.5 1.0 3.0	V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = 0.5\text{A}, I_B = 0.1\text{A}$ $I_C = 1.0\text{A}, I_B = 0.25\text{A}$			1.0 1.2	V
f_T	Current Gain Bandwidth Product	$V_{CE} = 10\text{V}, I_C = 0.1\text{A}$	4			MHz

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted (Continued)

Symbol	Parameter	Conditions	Min.	Max.	Units
t_{ON}	Turn On Time	$V_{CC} = 125\text{V}, I_C = 1\text{A}, I_{B1} = 0.2\text{A}$ $I_{B2} = -0.2\text{A}, R_L = 125\Omega$		1.1	μs
t_{STG}	Storage Time			4.0	μs
t_F	Fall Time			0.7	μs

Thermal Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$R_{\theta JC}$	Thermal Resistance Junction-Case	48	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	125	$^\circ\text{C/W}$

Typical Performance Characteristics

Figure 1. Static Characteristic

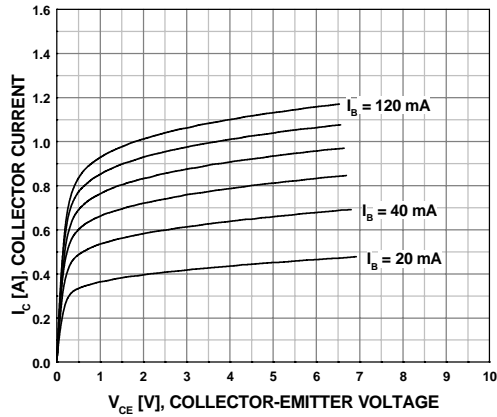


Figure 2. DC Current Gain

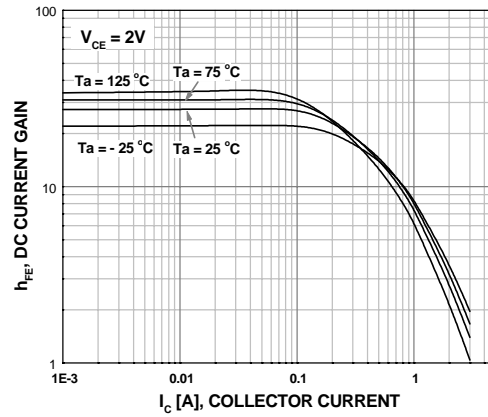


Figure 3. Collector-Emitter Saturation Voltage

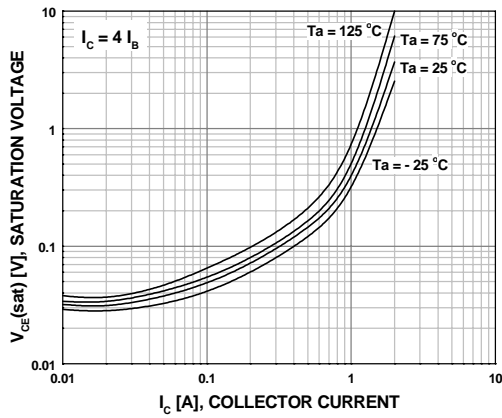


Figure 4. Base-Emitter Saturation Voltage

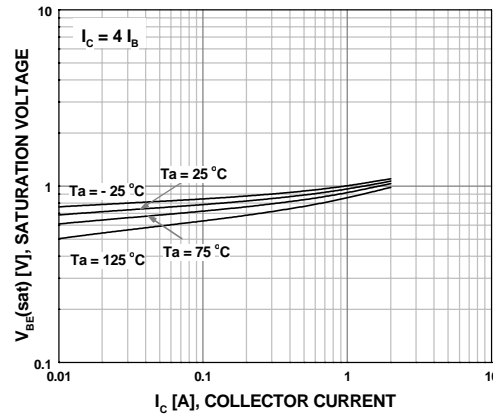


Figure 5. Resistive Load Switching Time

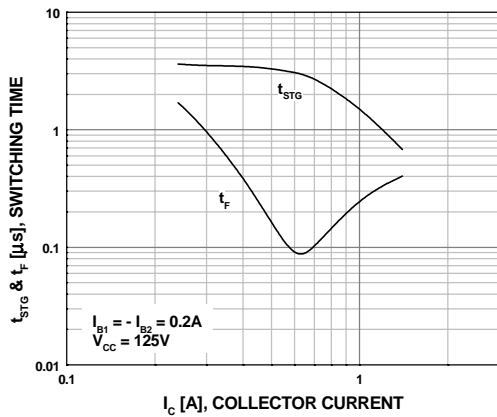
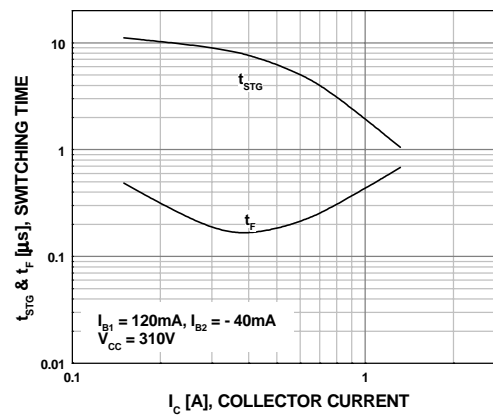


Figure 6. Resistive Load Switching Time



Typical Performance Characteristics (Continued)

Figure 7. Forward Biased Safe Operating Area

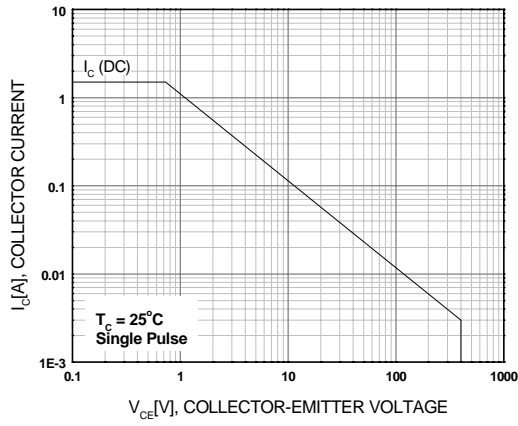


Figure 8. Reverse Biased Safe Operating Area

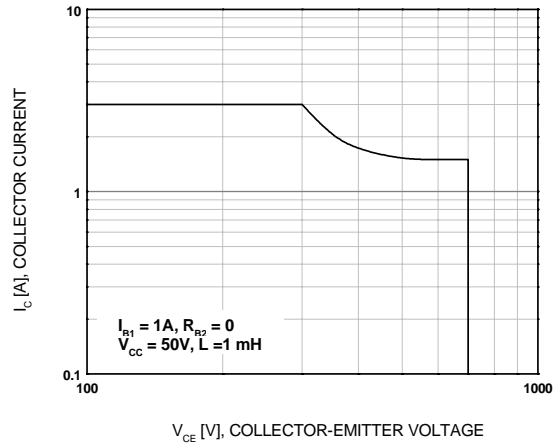
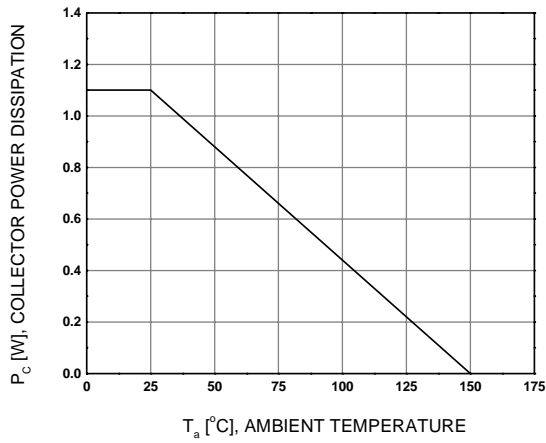
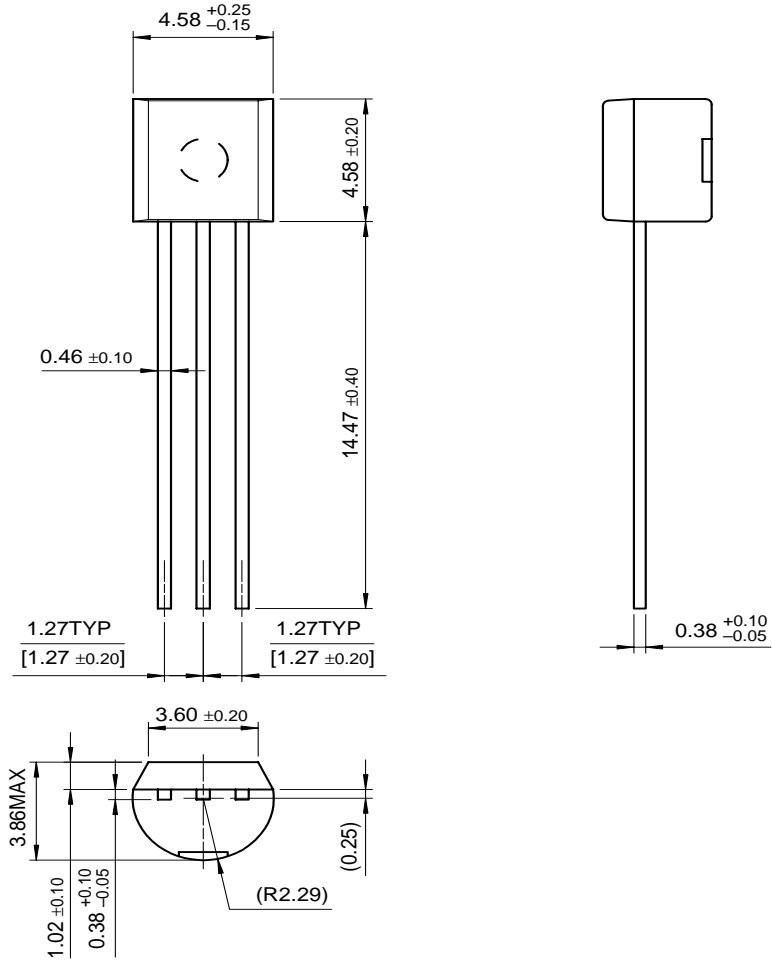


Figure 9. Power Derating



Mechanical Dimensions

TO-92



Dimensions in Millimeters

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